

WHAT IS CLAIMED IS:

1. A method of making a chip device, the method comprising:
 providing a bumped die including a plurality of solder bumps thereon;
 providing a leadframe including source and gate connections;
 placing the bumped die on the leadframe such that the solder bumps
 contact the source and gate connections;
 providing a copper clip;
 attaching the copper clip to a backside of the bumped die with solder paste
 such that the coupler clip contacts drain regions of the bumped die and a lead rail; and
 reflowing the solder paste and solder bumps.

2. A method in accordance with claim 1 wherein the solder paste is
 placed on the backside of the bumped die prior to attaching the copper clip.

3. A method in accordance with claim 1 wherein the solder paste is
 placed on the copper clip prior to attaching the copper clip.

4. A method in accordance with claim 1 wherein the solder bumps are
 reflowed prior to attaching the copper clip.

5. A chip device comprising:
 a leadframe including source and gate connections;
 a bumped die including solder bumps on a top side, the bumped die being
 attached to the leadframe such that the solder bumps contact the source and gate
 connections; and
 a copper clip attached to a backside of the bumped die such that the
 coupler clip contacts drain regions of the bumped die and a lead rail.

6. A chip device in accordance with claim 5 wherein the copper clip
 is attached to the bumped die with solder paste.

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